



PIN DNE -REFERENCE

WDFNW8 3.3x3.3, 0.65P

CASE 515AQ **ISSUE O**

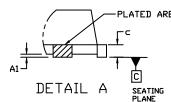
В

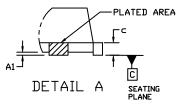
E1

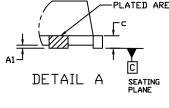
DATE 30 APR 2021

NOTES:

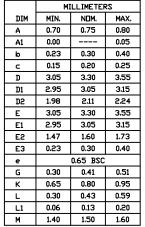
- 1. DIMENSIONING AND TOLERANCING PER.ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION DI AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

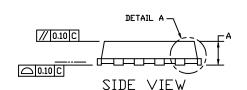






DETAIL B





2 3

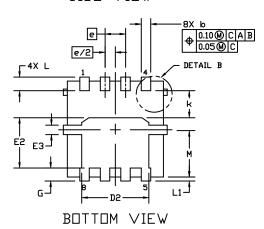
TOP VIEW

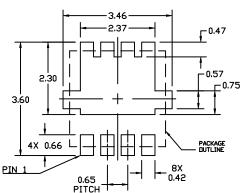
6 5





DETAIL B ALTERNATE CONSTRUCTION





RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

= Assembly Location Α

= Year WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

(Note: Microdot may be in either location)

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